



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-28
Contact Name *	Refer to Supplier Comment section		
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AARE*UAL3CCP	A	0959	2017-06-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	520.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	80	gull wing	
Comment	Package: TQFP 80 14x14x1.0 2.0 ExpadDown. MDF valid for CPs: L9300TD80T-TR and L9300TD80T			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	6.73	die backside metal-leadframe alloy & metal	12938

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AARE*UAL3CCP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	23.026	mg	supplier	die	Silicon (Si)	7440-21-3		20.809	mg	903722	40019
				supplier	metallization	Aluminium (Al)	7429-90-5		0.049	mg	2128	94
				supplier	metallization	Copper (Cu)	7440-50-8		1.289	mg	55978	3479
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	87	4
				supplier	metallization	Platinum (Pt)	7440-06-4		0.089	mg	3865	171
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	347	15
				supplier	metallization	Tungsten (W)	7440-33-7		0.073	mg	3170	140
				supplier	Passivation	Silicon Nitride	12033-89-5		0.042	mg	1824	81
				supplier	Passivation	Silicon Oxide	7631-86-9		0.320	mg	13897	615
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.012	mg	521	23
				supplier	back side metallization	Gold (Au)	7440-57-5		0.032	mg	1390	62
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.059	mg	2562	113
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	130	6
				supplier	polymer die coating	Polyimide AH 1200	Proprietary		0.239	mg	10379	460
				Leadframe	Copper & its alloys	191.304	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Nickel (Ni)	7440-02-0						5.708	mg	29837	10977
supplier	alloy	Magnesium (Mg)	7439-95-4						0.285	mg	1490	548
supplier	alloy	Silicon (Si)	7440-21-3						1.237	mg	6466	2379
supplier	metallization	Nickel (Ni)	7440-02-0						0.961	mg	5023	1848
supplier	metallization	Palladium (Pd)	7440-05-3						0.031	mg	162	60
supplier	metallization	Gold (Au)	7440-57-5						0.029	mg	152	56
supplier	metallization	Silver (Ag)	7440-22-4						0.029	mg	152	56
Die attach	Other Organic Materials	5.359	mg	supplier	glue	Silver (Ag)	7440-22-4		4.796	mg	894943	9220
				supplier	glue	isobornyl Methacrylate	7534-94-3		0.402	mg	75014	773
				supplier	glue	Bismaleimide resin	35325-39-4		0.161	mg	30043	310
				supplier	wire	Copper (Cu)	7440-50-8		4.403	mg	1000000	8467
Encapsulation	Other Organic Materials	295.908	mg	supplier	mold compound	Silica, vitreous	60676-86-0		255.664	mg	863998	491662
				supplier	mold compound	Epoxy Resin	25068-38-6		22.193	mg	75000	42679
				supplier	mold compound	Phenol Resin	29690-82-2		14.795	mg	49999	28452
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.480	mg	5001	2846
				supplier	mold compound	Quartz	14808-60-7		0.888	mg	3001	1708
supplier	mold compound	Carbon black	1333-86-4		0.888	mg	3001	1708				